Title: CHEMICAL VAPOR DEPOSITION OF TITANIUM

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21 83.

(New) The via of claim \$1, further including a titanium nitride layer interposed between the second layer and the fill.

W/V X 34

N

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II N

(New) The via of claim 78, wherein the first layer is coupled to a sidewall of the contact opening.

(New) The via of claim 78, wherein the first layer is coupled to a high aspect ratio contact opening.

## **REMARKS**

Currently claims 51-56 and 60-85 are pending in the application. The Applicant respectfully requests that the preliminary amendment described herein be entered into the record prior to examination and consideration of the above-identified application. The Examiner is invited to contact Applicant's Representatives at the below-listed telephone number if there are any questions regarding this Preliminary Amendment or if prosecution of this application may be assisted thereby.

Respectfully submitted,

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By their Representatives,

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## CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

CHEMICAL VAPOR DEPOSITION OF TITANIUM Applicant: Gurtej Singh Sandhu et al.

The paragraph beginning on page 1, line 4.

This application is a Divisional of U.S. Application No. 09/489,187, filed on January 20, 2000, which is a continuation-in-part of U.S. Application Serial No. 09/030,705, filed February 25, 1998, now issued as U.S. Patent 6,143,362 on November 7, 2000, which is hereby incorporated by reference in its entirety.

